

DIGI-KEY STANDARD

DKS-SOLDERPASTE15G-ND

Solder Paste No-Clean
Sn63/Pb37 in 5cc Syringe 15g
T3 Mesh



Product Highlights

- Printing speeds up to 100mm/sec
- Long stencil life
- Wide process window
- Clear residue
- Low voiding
- Excellent wetting compatibility on most board finishes
- Dispense grade
- Compatible with enclosed print heads
- Passed BONO test

Specifications

Alloy:	SN63/Pb37
Mesh Size:	T3
Micron Range:	25-45
Flux Type:	Synthetic No-Clean
Flux Classification:	RELO
Metal Load:	88% Metal by Weight
Melting Point:	183°C (361°F)
Packaging:	5cc/15g syringe
Shipped with:	Plunger, syringe tip and cap

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 2 Directive 2011/65/EU:	No

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	>100MΩ (No-Clean)
Track Value	IPC-TM-650: 2.4.44	44g
Viscosity - Malcom @ 10RPM/25°C (x10 ³ mPa/s)	IPC-TM-650: 2.4.34.4	Print: 210-300, Dispense: 100-140
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains Lead (Pb) CAS# 7439-92-1 No other SVHC present

Storage and Handling

Do not freeze. Refrigerate at 3-8°C (37-46°F). Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Shelf Life

Refrigerated: >12 months

Unrefrigerated: 6 months

Guaranteed for 12 months from date of manufacture regardless of refrigeration.

Warranty

Guaranteed for 12 months from date of manufacture regardless of refrigeration. Please retain original bill of sale and solder paste in original container as we may request its return for internal R&D testing purposes.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F)

>4 hours @ 50-70% RH 22-28°C (72-82°F)

Process for Soldering Surface Mount Technology (SMT) Devices to Printed Circuit Boards (PCBs):

1. Visually inspect the solder paste before use to ensure it is desired consistency. Do not use if solder paste is dried out or clumpy.
2. Apply solder paste to the PC Board pads using stencil printing machine, foil stencil & squeegee, or dot dispensing.
3. Carefully place SMT device using pick & place machine, tweezers, or vacuum pen.
4. Using machine, pick or tweezers gently press SMT device down into solder paste to ensure good contact.
5. Reflow using reflow oven, bottom heater, or hot air gun. Monitor temperature near PC Board with thermal probe to achieve a good reflow profile.
6. Allow PC Board to cool down.
7. Inspect solder joints for open and short circuits.
 - If rework is required: apply DKS-FLUXPEN10ML-ND and use soldering iron to reheat joints. Extra flux helps ensure solder will flow where needed and avoid short circuits.
8. If desired, remove excess flux using isopropyl alcohol and lint free wipes or cotton swabs.

Printer Operation

Print Speed: 25-100mm/sec

Squeegee Pressure: 70-250g/cm of blade

Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA)

Recommended Profile

Reflow profile for Sn63/Pb37 solder assembly, designed as a starting point for process optimization.

